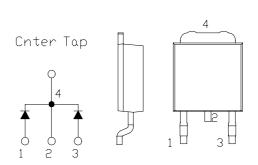
Nihon Inter Electronics Corporation

$\textbf{SBD} \quad \mathrm{Type} \,:\, EA60QC03L\text{-}F$

OUTLINE DRAWING

FEATURES

- * TO-252AA Case, Surface Mount Device
- * Dual Diodes Cathode Common
- * Low Forward Voltage drop
- * Low Power Loss
- * High Surge Capability
- * 30 Volts thru 100 Volts Types Available
- * Packaged in 16mm Tape and Reel



Maximum Ratings

Approx Net Weight:0.30g

Rating		Symbol	EA60QC03L-F			
Repetitive Peak Reverse Voltage		V _{RRM}	30			V
Average Rectified Output Current	P.C.Board mounted *	Io	2.0	Ta=20°C	50Hz Full Sine Wave	A
	-		6.0	Tc=111°C	Resistive Load	
RMS Forward Current		I _{F(RMS)}		6.66		
Surge Forward Current		Ifsm		50Hz Full Sine Wave,1cycle, Non-repetitive		A
Operating JunctionTemperature Range		Tjw	- 40 to + 150			°C
Storage Temperature Range		Tstg	- 40 to + 150			°C

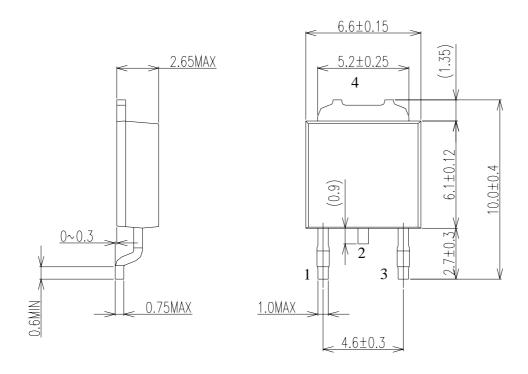
Electrical • Thermal Characteristics

Characteristics		Symbol	Conditions	Min	Тур	Max	Unit
Peak Reverse Current		I_{RM}	Tj=25°C,V _{RM} =V _{RRM} per Arm	-	-	3.0	mA
Peak Forward Voltage		$V_{\rm FM}$	Tj=25°C,I _{FM} = 3A per Arm	-	-	0.45	V
Thermal	Junction to Ambient	Rth(j-a)	P.C.Board mounted *	-	-	80	°C/W
Resistance	Junction to Case	Rth(j-c)	-	-	-	5	°C/W

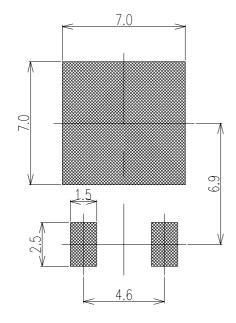
^{*} Print Land = 20x20 mm

Nihon Inter Electronics Corporation

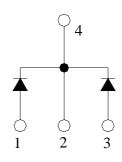
EA60QC03L-F OUTLINE DRAWING (Dimensions in mm)



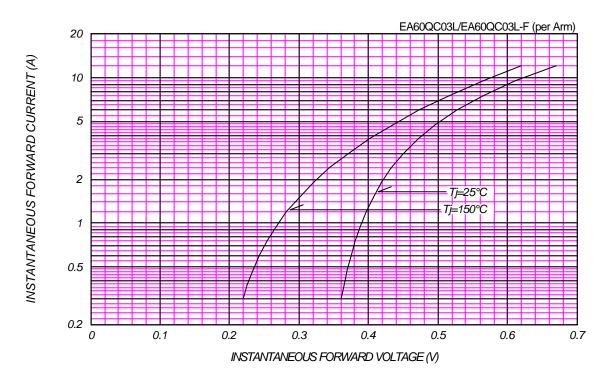
Soldering PAD

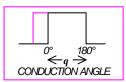


Center Tap

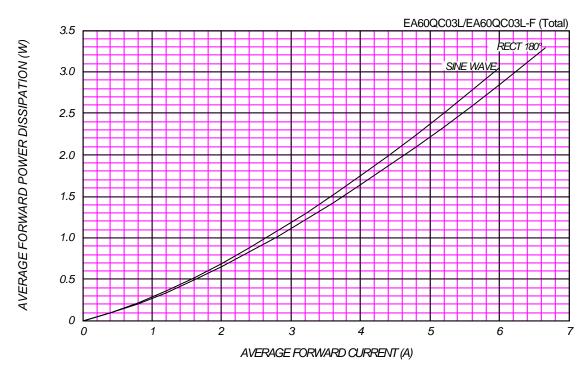


FORWARD CURRENT VS. VOLTAGE

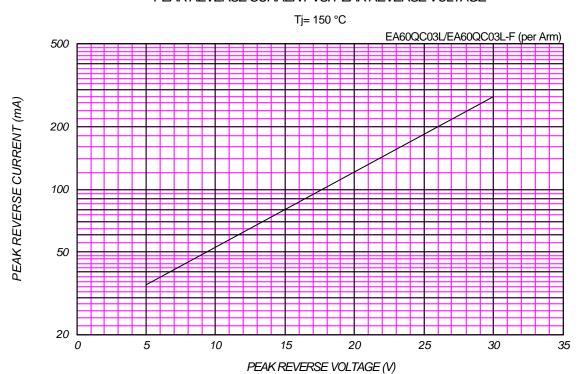




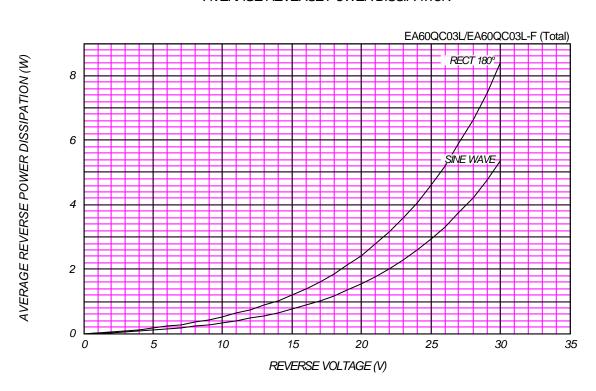
AVERAGE FORWARD POWER DISSIPATION

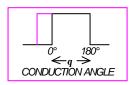


PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGE

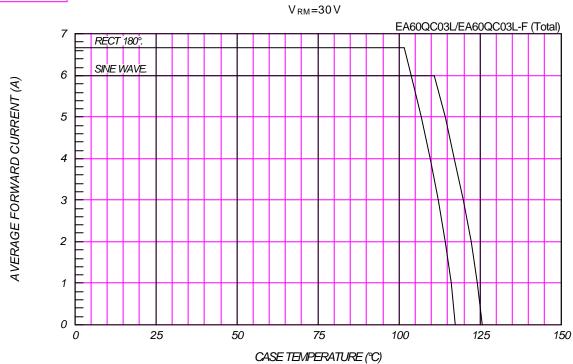


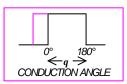
AVERAGE REVERSE POWER DISSIPATION



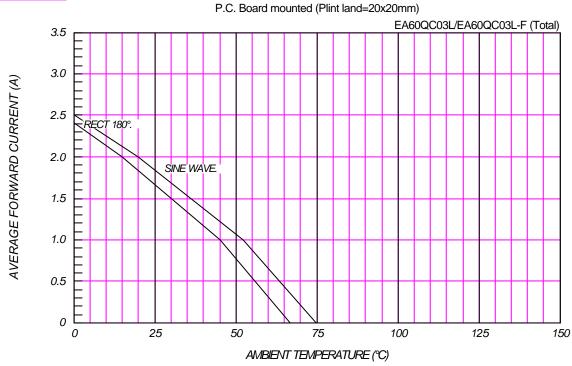


AVERAGE FORWARD CURRENT VS. CASE TEMPERATURE



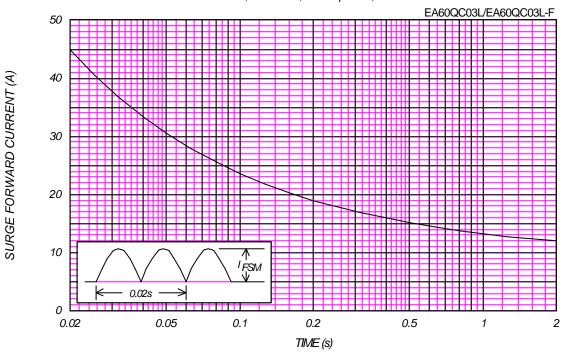


AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE



SURGE CURRENT RATINGS

f=50Hz,Sine Wave,Non-Repetitive,No Load



JUNCTION CAPACITANCE VS. REVERSE VOLTAGE

